Product data sheet

1. General description

Dual ultrafast power diode in a SOT404 (D2PAK) surface-mountable plastic package.

2. Features and benefits

- · High reverse voltage surge capability
- High thermal cycling performance
- Low thermal resistance
- Very low on-state loss
- · Soft recovery characteristic minimizes power consuming oscillations
- Surface-mountable package

3. Applications

· Output rectifiers in high-frequency switched-mode power supplies

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Values | | | Unit | |
|--------------------|---------------------------------|------------------------------------------------------------------------------------------------------------------------------------|--------|---|------|------|----|
| Absolute | maximum rating | | | | | | |
| V_{RRM} | repetitive peak reverse voltage | | | 2 | 00 | | V |
| I _{O(AV)} | average output current | $δ$ = 0.5; square-wave pulse; $T_{mb} \le 115$ °C; both diodes conducting; Fig. 1; Fig. 2 | 20 | | А | | |
| I _{RRM} | repetitive peak reverse current | $\delta = 0.001; t_p = 2 \mu s;$ | 0.2 | | А | | |
| V_{ESD} | electrostatic discharge voltage | HBM; C = 250 pF; R = 1.5 k Ω ; all pins | 8 | | kV | | |
| Static ch | aracteristics | | | | | | |
| V _F | forward voltage | I _F = 8 A; T _j = 150 °C; <u>Fig. 4</u> | | - | 0.72 | 0.85 | V |
| | | I _F = 20 A; T _j = 25 °C | | - | 1 | 1.15 | V |
| Dynamic | characteristics | | | | | | |
| t _{rr} | reverse recovery time | $I_F = 1 \text{ A}$; $V_R = 30 \text{ V}$; $dI_F/dt = 100 \text{ A/}\mu\text{s}$; $T_J = 25 \text{ °C}$; ramp recovery; Fig. 5 | | - | 20 | 25 | ns |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|------------------------|--------------------|----------------|
| 1 | A1 | anode 1 | F-F | |
| 2 | K | cathode [1] | | A4 N . 14 A2 |
| 3 | A2 | anode 2 | | A1 A2 |
| mb | К | mounting base; cathode | 1 TO-263 (D2PAK) | K sym125 |

^[1] it is not possible to make a connection to pin 2 of the SOT404 package

6. Ordering information

Table 3. Ordering information

| Type number | Package | | | | | | |
|-------------|---------|----------------------------------------------------------------------------------|---------|--|--|--|--|
| | Name | Description | Version | | | | |
| BYV32EB-200 | D2PAK | plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) | SOT404 | | | | |

7. Marking

Table 4. Marking codes

| Type number | Marking codes |
|-------------|---------------|
| BYV32EB-200 | BYV32EB-200 |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Values | Unit |
|--------------------|-------------------------------------|-----------------------------------------------------------------------------------------|------------|------|
| V_{RRM} | repetitive peak reverse voltage | | 200 | V |
| V_{RWM} | crest working reverse voltage | | 200 | V |
| V_R | reverse voltage | DC | 200 | V |
| I _{O(AV)} | average output current | $δ$ = 0.5; square-wave pulse; $T_{mb} \le 115$ °C; both diodes conducting; Fig 1; Fig 2 | 20 | А |
| I _{FRM} | repetitive peak forward current | $δ = 0.5$; $t_p = 25 \ \mu s$; $T_{mb} \le 115 \ ^{\circ}C$; per diode | 20 | А |
| I _{FSM} | non-repetitive peak forward current | t_p = 10 ms; sine-wave pulse; $T_{j(init)}$ = 25 °C; per diode | 125 | А |
| | | t_p = 8.3 ms; sine-wave pulse; $T_{j(init)}$ = 25 °C; per diode | 137 | А |
| I _{RRM} | repetitive peak reverse current | δ = 0.001; t _p = 2 µs; per diode | 0.2 | А |
| I _{RSM} | non-repetitive peak reverse current | t_p = 100 μ s; per diode | 0.2 | А |
| T _{stg} | storage temperature | | -40 to 150 | °C |
| T _j | junction temperature | | 150 | °C |
| V _{ESD} | electrostatic discharge voltage | HBM; all pins; C = 250 pF; R = 1.5 kΩ | 8 | kV |

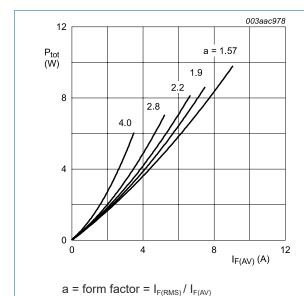


Fig. 1. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

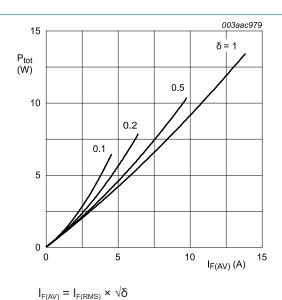


Fig. 2. Forward power dissipation as a function of average forward current; square waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|-----------------------|---------------------------------------------------|---------------------------------------------------|-----|-----|-----|------|
| R _{th(j-mb)} | thermal resistance from junction to | with heatsink compound; both diodes conducting | - | - | 1.6 | K/W |
| | mounting base | with heatsink compound; per diode; Fig 3 | - | - | 2.4 | K/W |
| R _{th(j-a)} | thermal resistance from junction to ambient | | - | 60 | - | K/W |

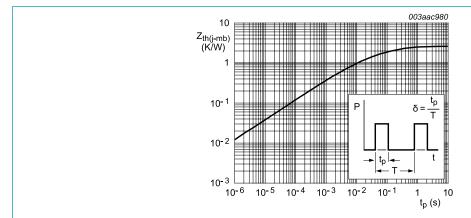
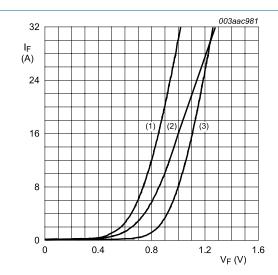


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|-----------------|--------------------------|----------------------------------------------------------------------------------------------------------------------------------------|-----|------|------|------|
| Static cha | racteristics | | | | | |
| V_{F} | forward voltage | I _F = 8 A; T _j = 150 °C; <u>Fig. 4</u> | - | 0.72 | 0.85 | V |
| | | I _F = 20 A; T _j = 25 °C | - | 1 | 1.15 | V |
| I _R | reverse current | V _R = 200 V; T _j = 25 °C | - | 6 | 30 | μΑ |
| | | V _R = 200 V; T _j = 100 °C | - | 0.2 | 0.6 | mA |
| Dynamic | characteristics | | | | | |
| Q _r | recovered charge | $I_F = 2 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 20 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}$ | - | 8 | 12.5 | nC |
| t _{rr} | reverse recovery time | $I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; \text{ ramp recovery; } Fig. 5$ | - | 20 | 25 | ns |
| | | I_F = 0.5 A to I_R = 1 A; T_j = 25 °C; measured at I_R = 0.25 A; step recovery; Fig. 6 | - | 10 | 20 | ns |
| V _{FR} | forward recovery voltage | $I_F = 1 \text{ A}$; $dI_F/dt = 10 \text{ A/}\mu\text{s}$; $T_j = 25 \text{ °C}$; Fig. 7 | - | - | 1 | V |



(1) T_j = 150 °C; typical values

(2) $T_j = 150$ °C; maximum values

(3) $T_j = 25$ °C; maximum values

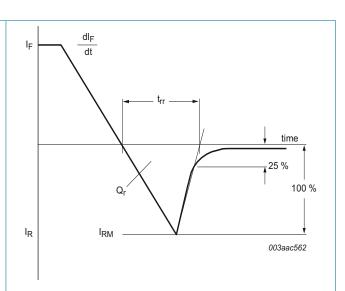


Fig. 5. Reverse recovery definitions; ramp recovery



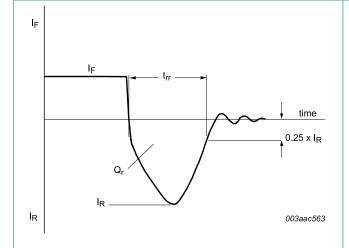


Fig. 6. Reverse recovery definitions; step recovery

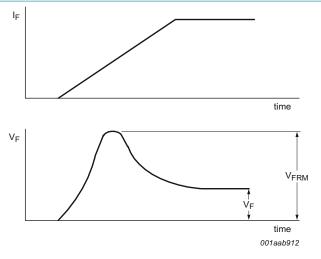
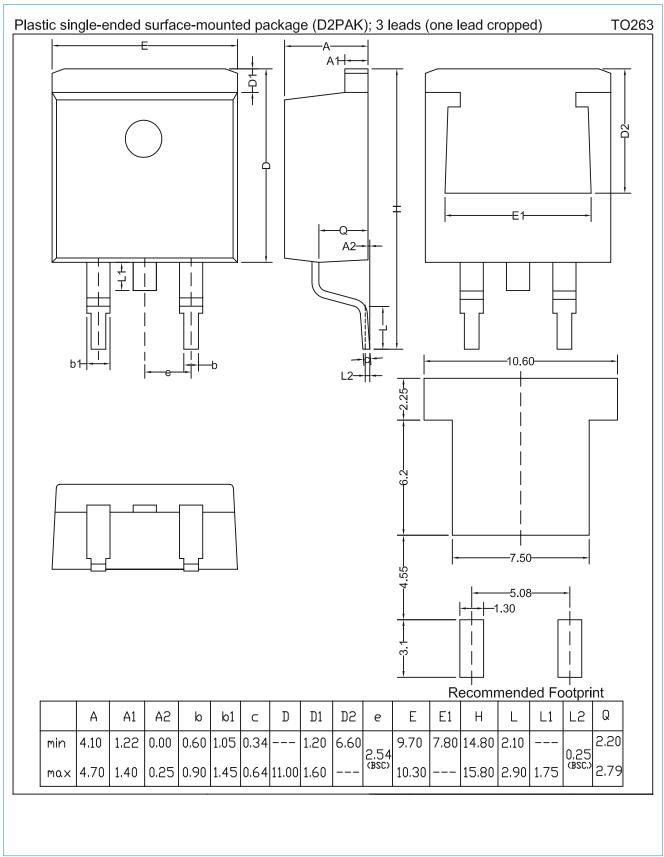


Fig. 7. Forward recovery definitions

11. Package outline



12. Legal information

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|--------------------------------------|--------------------|---------------------------------------------------------------------------------------|
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